

Abstract

A plate is placed near a substrate held by a substrate holding section. A treating liquid is ejected from a treating liquid ejecting section, thereby plating the substrate electrolessly. The treating liquid flows through the gap between the substrate and the plate. Therefore a flow of the treating liquid occurs on the substrate. As a result, a fresh treating liquid can be supplied onto the substrate. Thus, a plating film can be formed very uniformly on the substrate even if the amount of treating liquid is small.